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TIDA-01232 REV B Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C2, C3, C5, C11, C12, C14, C15, C19	8	10uF	GRM21BR61C106KE15L	MuRata	CAP, CERM, 10 µF, 16 V, +/- 10%, X5R, 0805	0805
2	C4, C7, C10, C16, C18	5	47uF	GRM219R60G476ME44D	MuRata	CAP, CERM, 47 µF, 4 V, +/- 20%, X5R, 0805	0805
3	C6, C8, C17	3	0.01uF	GRM188R71H103KA01D	MuRata	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X7R, 0603	0603
4	C9	1	68uF	TPSC686K016R0200	AVX	CAP, TA, 68 µF, 16 V, +/- 10%, 0.2 ohm, SMD	6032-28
5	D1, D2, D3, D4, D5	5	5.6V	SMAZ5V6-13-F	Diodes Inc.	Diode, Zener, 5.6 V, 1 W, SMA	SMA
6	J1, J12, J13	3		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
7	J3, J4, J15, J18	4		87898-0204	Molex	Header, 2.54 mm, 2x1, Gold, R/A, SMT	Header, 2.54 mm, 2x1, R/A, SMT
8	J5, J20	2		108-0907-001	Emerson Network Power	BANANA JACK, 15A, Insulated, Nylon, Yellow	940x438x438mil
9	J6, J17, J21	3		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
10	J7, J8, J22	3		SSQ-102-03-G-S	Samtec	Receptacle, 2.54mm, 2x1, Gold, TH	Receptacle, 2.54mm, 2x1, TH
11	J10	1		SSQ-106-03-G-D	Samtec	Receptacle, 2.54mm, 6x2, Gold, TH	Receptacle, 2.54mm, 6x2, TH
12	J11, J16	2		SSQ-104-03-G-D	Samtec	Receptacle, 2.54mm, 4x2, Gold, TH	Receptacle, 2.54mm, 4x2, TH
13	TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP10, TP11, TP12, TP13	11	SMT	5016	Keystone	Test Point, Compact, SMT	Testpoint_Keystone_Compact
14	U1, U2	2		TPS7A8500RGR	Texas Instruments	4-A, 6-µVRMS, RF, LDO Voltage Regulator, RGR0020A	RGR0020A
15	IPC1	0		TIDA-01232	Any	Printed Circuit Board	
16	C1, C13	0	68uF	TPSC686K016R0200	AVX	CAP, TA, 68 µF, 16 V, +/- 10%, 0.2 ohm, SMD	6032-28
17	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
18	J2, J14	0		87898-0204	Molex	Header, 2.54 mm, 2x1, Gold, R/A, SMT	Header, 2.54 mm, 2x1, R/A, SMT
19	J9, J19	0		342-10-104-00-591000	Mill-Max	Header, 100mil, 4x1, Gold, TH	Header, 100mil, 4x1, TH
20	R1, R2	0	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
21	SH-J1, SH-J2, SH-J3, SH-J4, SH-J5	0	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
22	TP1, TP9	0	SMT	5016	Keystone	Test Point, Compact, SMT	Testpoint_Keystone_Compact

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